FUJITSU

COMPACT HIGH POWER RELAY

1 POLE - 30A (For automotive applications)

FBR53 Series

FEATURES

- Compact for high density packaging
- High contact capability (30A continuous)
- High temperature grade (-40°C to 125°C)
- Contact arrangement Form U (form A)
- 60A inrush
- Coil wire temp. class F



Part Numbers

[Example]	FBR53	Ν	D12	- Y	-	RW
	(a)	(b)	(c)	(d)	(e)

(a)	Relay type	FBR53	: FBR53 series
(b)	Enclosure	N	: Plastic sealed type
(c)	Coil rated voltage	D12	: 912VDC Coil rating table at page 3
(d)	Contact material	Y	: Silver-tin oxide
(e)	Soldering	Nil RW	: Standard (Flow soldering) : Reflow capable (THR)

Actual markings does not carry the type name: "FBR"

E.g.: Ordering code: FBR53ND12-Y Actual marking: 53ND12-Y

Specifications

Item			FBR53	Remarks / conditions	
Contact Configuration			1 form U		
data	Material		Silver-tin oxide (AgSnO ₂)		
	Voltage drop		Max. 100 mV at 1A (12VDC open contact voltage) Average 1.5mΩ at 7A, 12VDC		
	Contact rating		25A, 14VDC	Resistive load	
	Max. carrying current		30A		
	Max. inrush current		60A	Reference	
	Min. switching load		1A 6VDC	Reference *	
Coil	Rated power consumption		600mW	At 20°C	
	Operate power consumption		220mW	At 20°C	
	Storage temperature range		-40°C ~ +125°C	No frost	
	Operating temperature range		-40°C ~ +125°C	No frost	
Timing	Operate		Max. 10ms	At nominal voltage	
data	Release		Max. 5ms	At nominal voltage (No diode)	
Life	Mechanical		Min. 10 x 10 ^e operations	without contact load	
	Electrical		Min. 100 x 10 ³ operations	14VDC, 25A resistive load	
Insula-	Insulation resistance		Min. 100M	At 500VDC initial	
tion	Dielectric withstanding voltage	Open contacts	500VAC (50/60Hz), 1 minute		
		Coil contact	500VAC (50/60Hz), 1 minute		
Other	Vibration resistance	Misoperation	10 to 200Hz, acceleration 44m/s²(4.5G) constant acceleration	Direction X, Y, Z, contact ON/OFF total 6 cycles	
		Endurance	10 to 200Hz, acceleration 44m/s²(4.5G) constant acceleration	Direction X, Y, Z, contact OFF total 6 hours	
	Shock resis- tance	Misoperation	100m/s² (11±1ms)	Direction X, Y, Z, contact ON/OFF total 36 times	
		Endurance	1,000m/s² (6±1ms)	Direction X, Y, Z, contact OFF total 18 times	
	Dimensions / weight		12.3 x15.7x14.0 mm / approx. 6g		
	Sealing		Sealed, cat III		

*: Minimum switching loads mentioned above are reference values. Please perform the confirmation test with actual load before production since reference values may vary according to switching frequencies, environmental conditions and expected reliability levels. Care shall be taken on the heat generated on PC board when maximum carrying current exceeds 10A. Please perform the confirmation test with actual conditions.

Coil Data

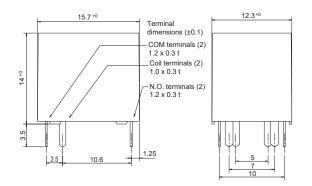
Coil code	Rated Coil Voltage (VDC)	Coil Resistance +/-10%(Ω)	Must Operate Voltage [*] (VDC)	Must Release Voltage [*] (VDC)
D09	9	135	5.4 6.8 (at 85°C)	0.7 0.9 (at 85°C)
D10	10	180	6.3 7.9 (at 85⁰C)	0.8 1.0 (at 85°C)
D12	12	240	7.3 9.2 (at 85°C)	1.0 1.3 (at 85⁰C)

Note: All values in the table are valid at 20°C and zero contact current, unless otherwise specified.

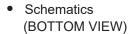
* Specified operated values are valid for pulse wave voltage. Please use at rated coil voltage. Please refer to characteristic data and set up adequate voltage in case of use at over voltage.

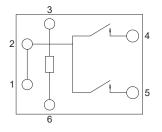
Dimensions

• Dimensions



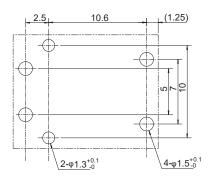
Dimensions of the terminals do not include thickness of pre-solder.





Pattern shall be designed to short-circuit #4 and #5 on the PC board.

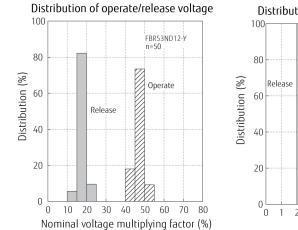
 PC Board Mouting Hole Layout (BOTTOM VIEW)

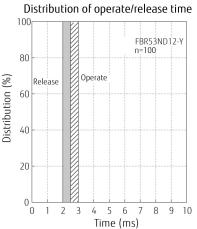


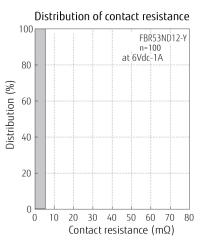
Tolerance of PC board mounting hole layout : ±0.1 unless otherwise specified.

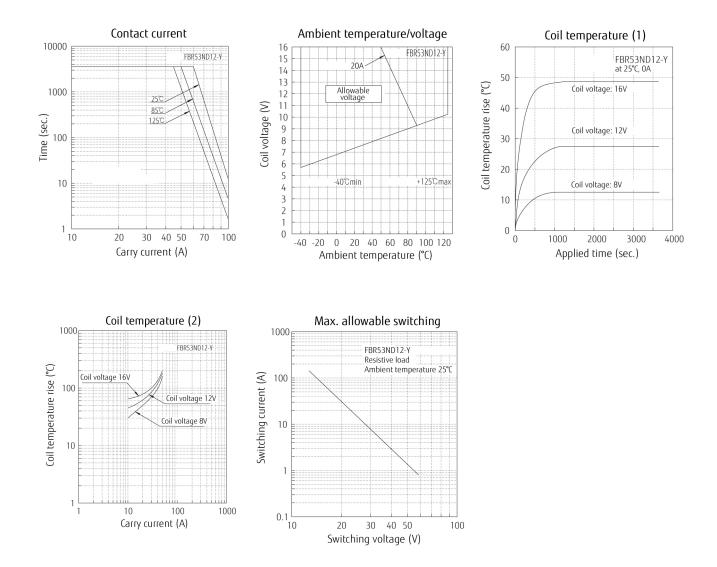
(): Reference value Unit: mm

Characteristic Data (Reference)









CAUTIONS

- All values mentioned in this datasheet are provided under ideal conditions. Please perform the confirmation test before actual use.
- Reflow soldering is prohibited for flow soldering type.
- Do not use relays in the atmosphere with sulfide gas, chloride gas or nitric oxide. Contact resistance may increase.
- · Do not use silicon or silicon-containing product or materials near relays. It may cause contact failure.

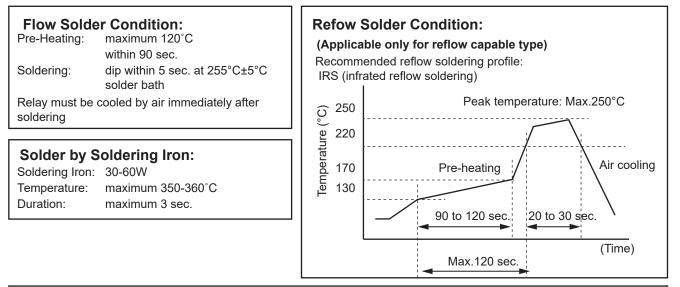
GENERAL INFORMATION

1. ROHS Compliance

 All relays produced by Fujitsu Components are compliant with RoHS directive 2011/65/EU, including commission delegated directive 2015/863.

2. Recommended lead free solder condition

- Lead free solder plating on relay terminals is Sn-3.0Ag-0.5Cu, unless otherwise specified. This material has been verified to be compatible with PbSn assembly process.
- Recommended solder for assembly: Sn-3.0Ag-0.5Cu.



Important Notes for reflow Soldering

- Temperature shall be measured at PC boartd uppler surface.
- Temperature at PC board upper surface may be changed depending on size of PC board, components mounted on the PC board and/or heating method. Please perform the confiramtion test with your actual PC board.
- This reflow condition is applicable only for reflow-capable relays. Do not reflow reflow-incapable relays.

We highly recommend that you confirm your actual solder conditions

3. Moisture Sensitivity

· Moisture Sensitivity Level standard is not applicable to electromechanical relays, unless otherwise indicated.

4. Tin Whiskers

• Dipped SnAgCu solder is known as presenting a low risk to tin whisker development. No considerable length whisker was found by our in house test.

Contact

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